Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	183	(semiconductor or die or chip or IC) same (guard$3 or protect$3) with scrib$3	USPAT	OR	ON	2005/09/14 13:17
L2	183	(semiconductor or die or chip or IC) same (guard$3 or protect$3) with scrib$3	USPAT	OR	ON	2005/09/14 13:20
L3	73	(semiconductor or die or chip or IC) same (guard$3 or protect$3) with scrib$3 near (ring or line)	USPAT	OR	ON	2005/09/14 14:21
L4	21	(semiconductor or die or chip or IC) and (guard$3 or protect$3) near (line or ring) with scrib$3 near (ring or line)	USPAT	OR	ON	2005/09/14 14:17
L5	1	(semiconductor or die or chip or IC) and scrib$3 near (ring or line) with function with (guard$3 or protect$3)	USPAT	OR	ON	2005/09/14 14:19
L6	3	(semiconductor or die or chip or IC) and scrib$3 near (ring or line) with work$3 with (guard$3 or protect$3)	USPAT	OR	ON	2005/09/14 14:21
L7	125	(semiconductor or die or chip or IC) and scrib$3 near (ring or line) with (guard$3 or protect$3)	USPAT	OR	ON	2005/09/14 15:16
L8	104	7 not 4	USPAT	OR	ON	2005/09/14 14:22
L9	64	scrib$3 near (ring or line) with (guard$3 or protect$3) with (semiconductor or die or chip or IC)	USPAT	OR	ON	2005/09/14 15:16
L10	1	"5721151".PN.	USPAT; USOCR	OR	OFF	2005/09/14 15:28
L21	774	257/620	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/14 16:37
L22	661	257/620	USPAT	OR	ON	2005/09/14 16:38
L23	113	21 not L22	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/14 16:39

L24	661	21 not 23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/14 16:39
L25	102	257/483	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/14 16:47
L26	162	257/484	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/14 16:54
L27	5073	257/758	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/14 16:54
S1	19	"6399897" or "6165886" or "4914503"	USPAT	OR	OFF	2005/03/17 19:08
S2	11	"6362524" or "5583380" or "6212077" or "006545348"	USPAT	OR	OFF	2005/03/17 19:11
S3	34	"6300223" or "5831330" or "5834829" or "6028347"	USPAT	OR	OFF	2005/03/17 19:11
S4	37	"6300223" or "5831330" or "5834829" or "6028347" or "20010030358"	US-PGPUB; USPAT	OR	OFF	2005/03/17 19:18
S5	9	"5717245".pn. or "6028497".pn. or "5864092".pn. or "6105226".pn. or "5998245".pn. or "6028347".pn. or "5185654".pn. or "4868716".pn. or "6180876".pn.	US-PGPUB; USPAT	OR	OFF	2005/03/17 19:19
S6	17	"5831330"	USPAT	OR	OFF	2005/03/18 14:21
S7	23386	(semiconductor or die or chip or IC) with seal$3	USPAT	OR	ON	2005/03/18 14:22
S8	1656	(semiconductor or die or chip or IC) with seal$3 with ring	USPAT	OR	ON	2005/03/18 14:59
S9	675	257/620	USPAT	OR	ON	2005/09/14 16:37
S10	79	(semiconductor or die or chip or IC) with dummy with ring	USPAT	OR	ON	2005/03/18 16:22
S11	1	"5024970".PN.	USPAT; USOCR	OR	OFF	2005/03/18 16:00

S12	1	"5414297".PN.	USPAT; USOCR	OR	OFF	2005/03/18 16:00
S13	1	"5530280".PN.	USPAT; USOCR	OR	OFF	2005/03/18 16:00
S14	1	"5559362".PN.	USPAT; USOCR	OR	OFF	2005/03/18 16:00
S15	1	"5665655".PN.	USPAT; USOCR	OR	OFF	2005/03/18 16:01
S16	1	"5698892".PN.	USPAT; USOCR	OR	OFF	2005/03/18 16:01
S17	1	"5772906".PN.	USPAT; USOCR	OR	OFF	2005/03/18 16:01
S18	1	"5831330".PN.	USPAT; USOCR	OR	OFF	2005/03/18 16:01
S19	1	"5891808".PN.	USPAT; USOCR	OR	OFF	2005/03/18 16:03
S20	1	"5772906".PN.	USPAT; USOCR	OR	OFF	2005/03/18 16:04
S21	1	"5723385".PN.	USPAT; USOCR	OR	OFF	2005/03/18 16:08
S22	1	"4835592".PN.	USPAT; USOCR	OR	OFF	2005/03/18 16:16
S23	1	"5239191".PN.	USPAT; USOCR	OR	OFF	2005/03/18 16:16
S24	1	"5285082".PN.	USPAT; USOCR	OR	OFF	2005/03/18 16:16
S25	1	"6121677".PN.	USPAT; USOCR	OR	OFF	2005/03/18 16:16
S26	1	"6174789".PN.	USPAT; USOCR	OR	OFF	2005/03/18 16:17
S27	1	"6194739".PN.	USPAT; USOCR	OR	OFF	2005/03/18 16:17
S28	1337	(semiconductor or die or chip or IC) with (guard$3 or protect$3 or scrib$3) with ring	USPAT	OR	ON	2005/03/18 16:22
S29	1924	(semiconductor or die or chip or IC) with (guard$3 or protect$3 or scrib$3 or cutt$3) with ring	USPAT	OR	ON	2005/03/18 17:20
S30	1	"5818111".PN.	USPAT; USOCR	OR	OFF	2005/03/18 16:37
S31	1	"5834829".PN.	USPAT; USOCR	OR	OFF	2005/03/18 16:37
S32	1	"6190947".PN.	USPAT; USOCR	OR	OFF	2005/03/18 16:37
S33	1	"6207554".PN.	USPAT; USOCR	OR	OFF	2005/03/18 16:37

S34	1	"6271102".PN.	USPAT; USOCR	OR	OFF	2005/03/18 16:37
S35	1	"6271102".PN.	USPAT; USOCR	OR	OFF	2005/03/18 16:37
S36	1	"6291317".PN.	USPAT; USOCR	OR	OFF	2005/03/18 16:37
S37	1	"6294439".PN.	USPAT; USOCR	OR	OFF	2005/03/18 16:38
S38	1	"6534386".PN.	USPAT; USOCR	OR	OFF	2005/03/18 16:38
S39	126	257/483	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/14 16:46
S40	227	257/484	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/18 17:23
S41	25749	coefficient near thermal near expansion	USPAT	OR	OFF	2005/03/21 12:13
S42	0	coefficient near thermal near expansion with "/K"	USPAT	OR	OFF	2005/03/21 12:14
S43	7	coefficient near thermal near expansion with degree near "K"	USPAT	OR	OFF	2005/03/21 12:16
S44	0	coefficient near thermal near expansion with degree near "K" with ("Si" or silicon or silicone)	USPAT	OR	OFF	2005/03/21 12:17
S45	2	coefficient near thermal near expansion with degree near "K" same ("Si" or silicon or silicone)	USPAT	OR	OFF	2005/03/21 12:17
S46	3054	coefficient near thermal near expansion with ("Si" or silicon or silicone)	USPAT	OR	OFF	2005/03/21 12:18
S47	50	coefficient near thermal near expansion with ("Si" or silicon or silicone) with "K"	USPAT	OR	OFF	2005/03/21 12:53
S48	18	(semiconductor or die or chip or IC) with (guard$3 or protect$3 or scrib$3 or cutt$3) with ring and corner with (wider or bigger or wide or big or large)	USPAT	OR	OFF	2005/03/24 12:04

S49	7	(semiconductor or die or chip or IC) with (guard$3 or protect$3 or scrib$3 or cutt$3) with ring same corner with (wider or bigger or wide or big or large)	USPAT	OR	OFF	2005/03/24 12:09
S50	2	(semiconductor or die or chip or IC) with (guard$3 or protect$3 or scrib$3 or cutt$3) with ring same corner with (wider or bigger or wide or big or large)	US-PGPUB; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/14 13:16
S51	4854	257/758	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/24 20:50